



DATA SHEET

System in Package Sensor Fusion

Features and benefits

- System in Package (SiP) – Miniaturized and integrated form factor through Flex proprietary packaging process
- Self contained subsystem that frees host processor from sensor fusion workloads
- Low barrier for integration in new or existing products

KEY COMPONENTS

Integrated sensors and compute module

- QuickLogic EOS S3 - ARM Cortex M4-F up to 80Mhz with 512KB SRAM
- 64mb SPI flash
- Infineon DPS310 - Digital Barometric Pressure
- Infineon IM69D130 - Digital MEMS Microphone
- ST LSM6DSO – 6-axis IMU

For enquiries, please visit:
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INTERFACES

UART interfaces for debug, flashing, alarm conditions, raw sensor data

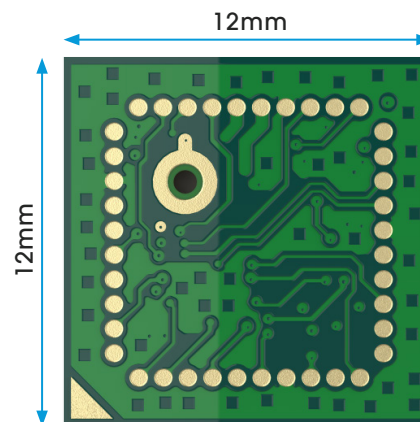
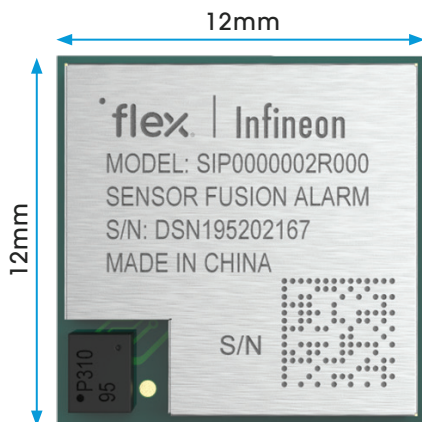
GPIOs: configurable for communication, control, test, alarm conditions

Flash Direct Access

SWD interface for debugging

POWER

Operational Power Supply: 1.8V-3.3V



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